DESCRIPTION

~~METHOD FOR POLISHING BOTH SURFACES OF WAFER~~

TECHNICAL FIELD

[0001]

The present invention relates to a double-side polishing method involving interposing a wafer between upper and lower turn tables, to which the respective polishing pads are attached, and simultaneously polishing both surfaces of the wafer.

BACKGROUND ART

[0002]

In manufacture of wafers, such as silicon wafers, conventionally, an ingot is sliced into wafers, the wafers are subjected to, in sequence, lapping, etching, and other processes, and at least a main surface of the wafers is then mirror-polished. This polishing process employs a single-side polishing apparatus for polishing one surface of wafers and a double-side polishing apparatus for simultaneously polishing both surfaces of wafers.

[0003]

A double-side polishing apparatus includes an upper turn table and a lower turn table, and polishing pads, which are typically made of a nonwoven fabric, are attached to the respective turn tables. FIG. 5 illustrates a four-ways type of a double-side polishing apparatus that has a planetary gear structure in which a sun gear 107 is disposed at the center and an internal gear 108 is disposed at the outer circumference. With such a double-side polishing apparatus, wafers are

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